

ABSTRACT OF THE DISCLOSURE

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2 A light emitting diode (LED) has a leadframe, at least one LED chip
3 and an encapsulant. The leadframe has a first and a second pin each having an
4 upper sealed portion and a bottom exposed portion. The upper sealed portion
5 on which the LED chip is mounted is covered by the encapsulant. The bottom
6 exposed portion is composed of a neck and a longitudinal conductor. The neck
7 is larger than the longitudinal conductor to increase the surface area and the
8 capability to dissipate heat. The neck may further have a transverse fin to
9 increase the surface area and heat dissipation. Therefore, the present invention
10 has a good heat-dissipating capability.